ASSOCIATION CELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both lev	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				als and Mfg Information				
upplier I	Information								,					
Company name*				ompany unique ID			Unique ID Authority				Response Date*			
nsemi										2025-05-15				
Contact Nan	me	Title - Contact			P	Phone - Contact*				Email - Contact*				
Product-En	v-Stewards		Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com			
uthorized 1	Representative*	Title - Representative			P	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			ľ	NA				Product-Env-Stewards@onsemi.com			
I	Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Date Version Manufacturing Site		Ianufacturing Site	W	eight*	UOM	Unit Type
	FDMS3660S-AU01 erTrench erStage		erTrench erStage A	symmet	2025-05-15			PBB		12	21.566	mg	Each	
Ianufact	curing Proccess Inform	ation												
Terminal Plating / Grid Array Material Terminal Base Alloy			Alloy J-S	STD-020 MSL R	MSL Rating Peak Process Body Temperature Max Time at Peal				Temperatu	re Numb	er of Reflow Cyc	eles		
N.	Matte Tin (Sn) - annealed		CU Alloy	1			260		C	30	second	s <b>3</b>		
omments														
<u>vel 1 - max</u>	ximum time at peak tempera	ture during sol	dering is 10-3	30 seconds										
or more in	formation regarding materia	al composition	please refer t	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominal contains a RoHS restricted substance inexcess encompass all such components. Supplier certi as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided by certification in this paragraph. If the Company	ted biphenyls and/or polybrominated dipheny of an applicable quantity limit, please indicate fies that it gathered the information it provident. Supplier acknowledges that Company will we relied on information provided by others in the supplier agrees that, at a minimum and the Supplier enter into a written agreements ource of the Supplier's liability and the Com-	2011/65/EU and implemented by the laws of the End ethers (each a "RoHS restricted substance") in except the below which, if any, RoHS exemption you believe in this form using appropriate methods to ensure rely on this certification in determining the compliant completing this form, and that Supplier may not have its suppliers have provided certifications regarding ent with respect to the identified part, the terms and capany's remedies for issues that arise regarding information in the provided certification in	sess of the applicable quantity limit identified able may apply. If the part is an assembly with low its accuracy and that such information is true annee of its products with European Union member ave independently verified such information. However, their contributions to the part, and those certifications of that agreement, including any warr	bove. If a homogeneous material within the part ver level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. It is involved in situations where Supplier has not ations are at least as comprehensive as the ranty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	19.1	mg	Supplier	Zinc (Zn)	7440-66-6		0.025	mg
i			Supplier	Iron (Fe)	7439-89-6		0.458	mg
			Supplier	Copper (Cu)	7440-50-8		18.617	mg
Die	1.6	mg	Supplier	Silicon (Si)	7440-21-3		1.6	mg
Die Attach Solder	1.936	mg	Supplier	Silver (Ag)	7440-22-4		0.0484	mg
			A	Lead (Pb)	7439-92-1	7a	1.7908	mg
			Supplier	Tin (Sn)	7440-31-5		0.0968	mg
Lead Frame	46.396	mg	Supplier	Silver (Ag)	7440-22-4		0.636	mg
			Supplier	Zinc (Zn)	7440-66-6		0.06	mg
			Supplier	Iron (Fe)	7439-89-6		1.1	mg
			Supplier	Copper (Cu)	7440-50-8		44.6	mg
Mold Compound-Black	43.59	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		2.18	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		40.1	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.31	mg
Plating	8.33	mg	Supplier	Tin (Sn)	7440-31-5		8.33	mg
Wire Bond	0.614	mg	Supplier	Gold (Au)	7440-57-5		0.581	mg
			Supplier	Copper (Cu)	7440-50-8		0.033	mg